

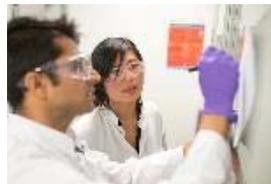


Multiphysics modelling of photo-polymerization in DLP printing process and validation



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Brightlands Materials Center

- **Public-private partnership** initiative founded March 19, 2015 by TNO and the Province of Limburg.
- Focusing on **sustainable** innovations in **polymers**.
- Three programs driven by **application challenges**, together with universities and industry partners.



Sustainable Buildings



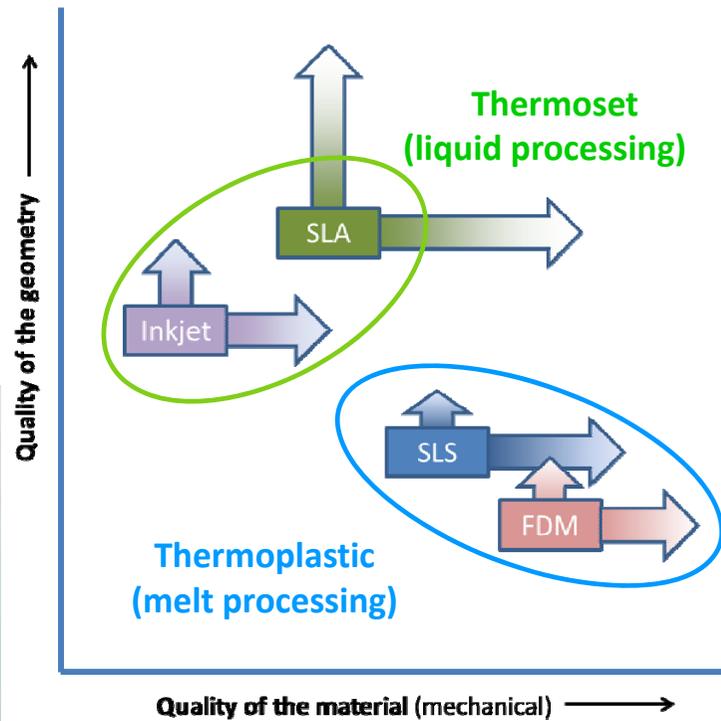
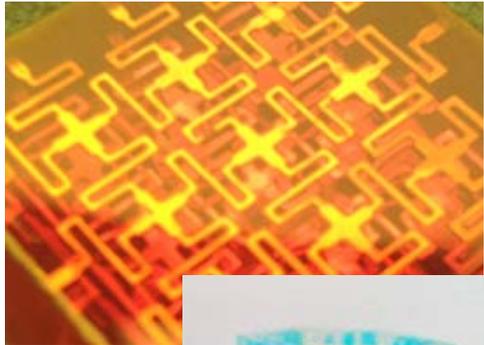
Additive Manufacturing



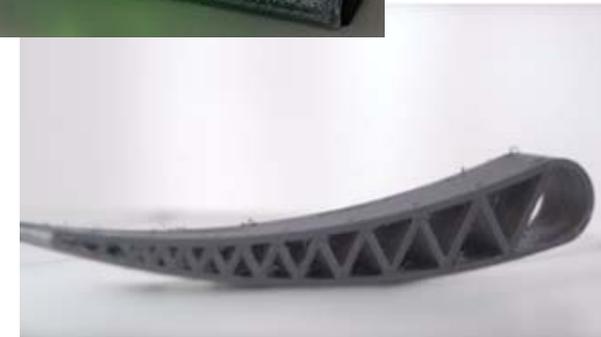
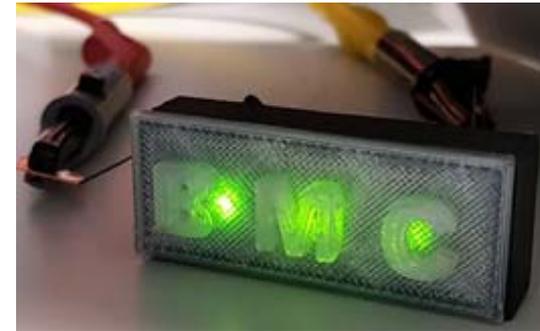
Lightweight Automotive

Additive Manufacturing Program – Focus

Multi-material photopolymer for new (responsive) functionalities



polymers with continuous fibers for reinforcement and sensing



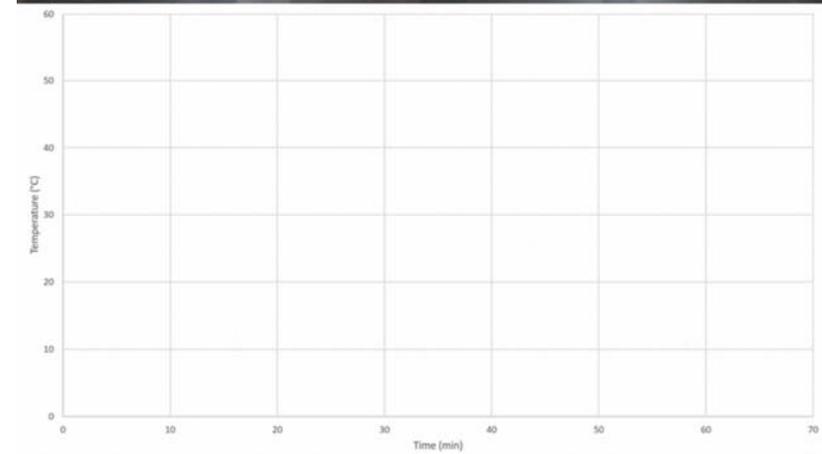
Materials Challenges

- Quality: warpage and residual stress, ...
- Stability: structural performance at high temperature and long term behavior, ...
- Multi-material, 4D printing and etc.

Warpage in products



Thermal stability





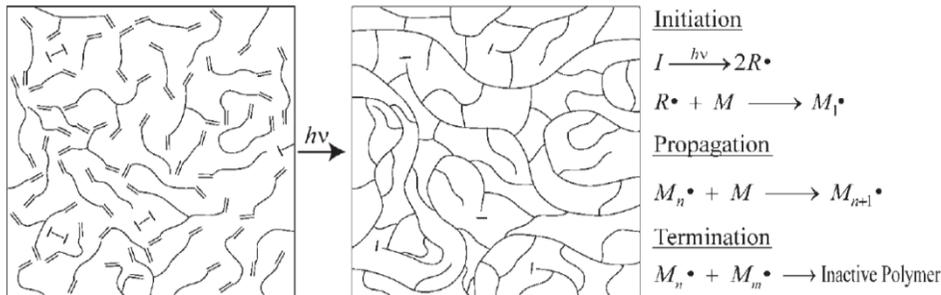
Objective

*To use **modeling and simulation** in order to link **materials and process** for further control in **SLA/DLP printing***

- Models are needed to understand and improve:
 - Process conditions* to meet or contribute to the object specifications
 - Material compositions* to meet or contribute to the object specifications

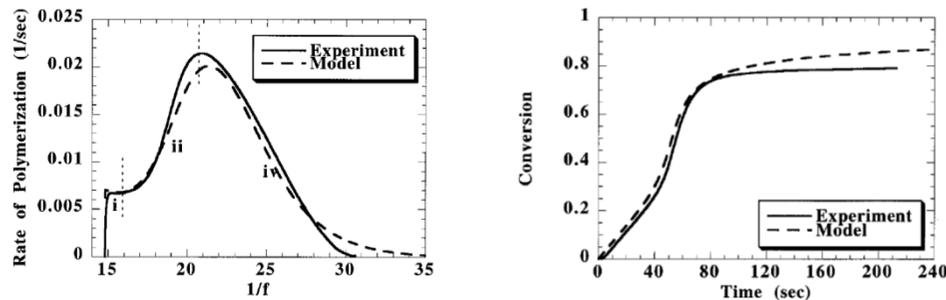
Photo-polymerization in SLA/DLP

- SLA: Stereolithography Apparatus; DLP: Digital Light Printing
- The photo-polymerization is the core of SLA/DLP technology.

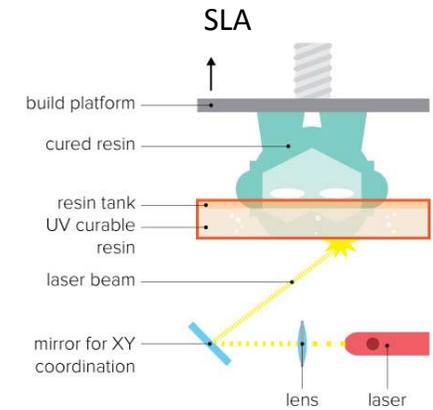


C.N. Bowman and C.J. Kloxin, 2008

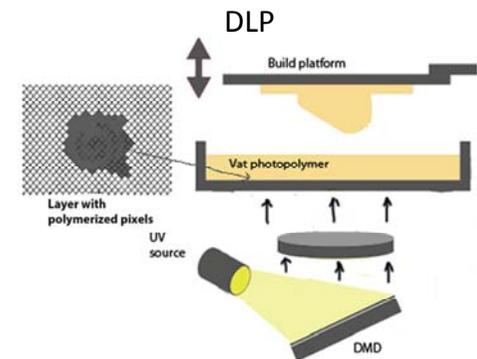
- The double-bond conversion can be used to present the reaction.



M.D. Goodner H.R. Lee and C.N. Bowman, 1997

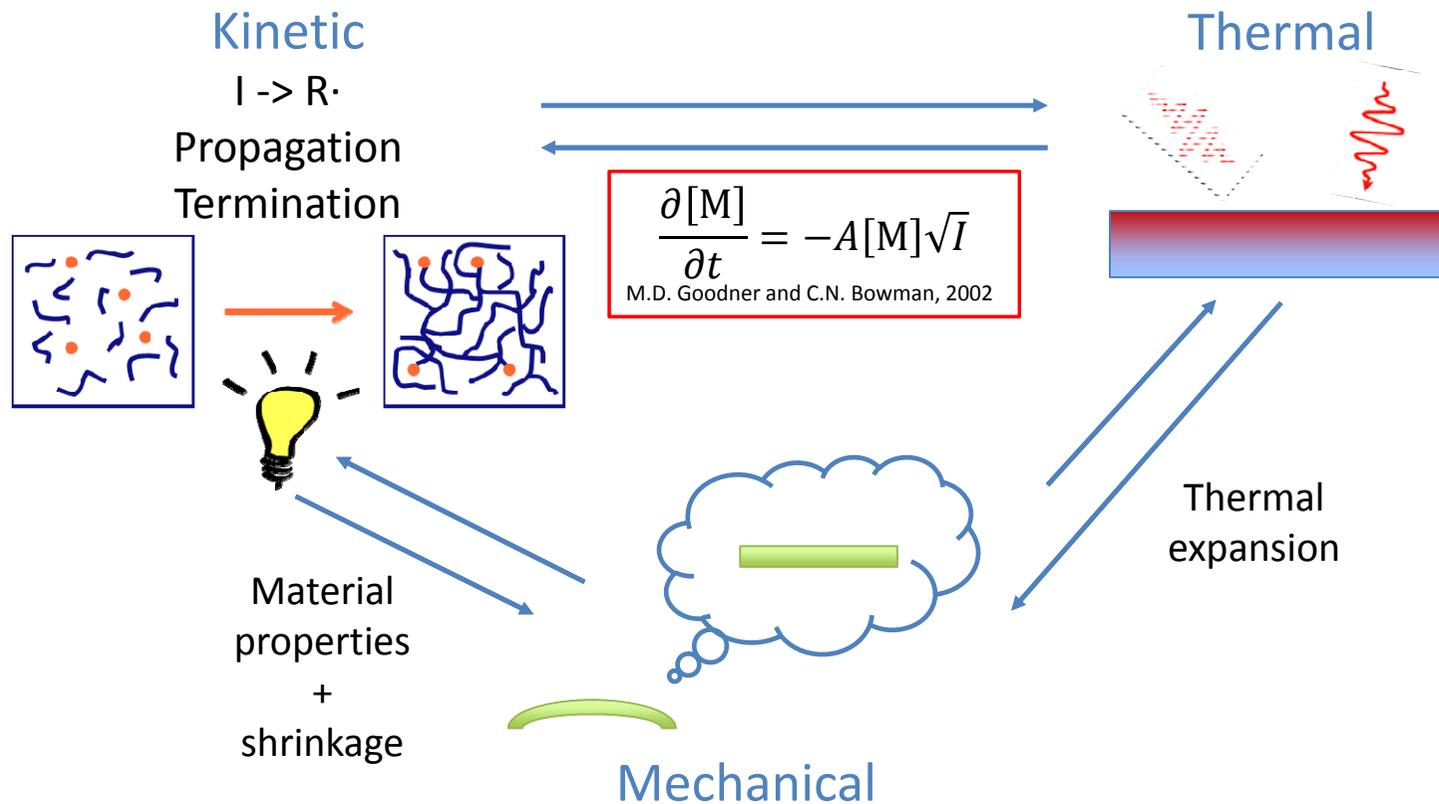


©<http://rookieelectronics.com/3d-printing-technologies-types/>



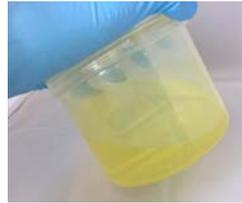
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Multiphysics Modelling



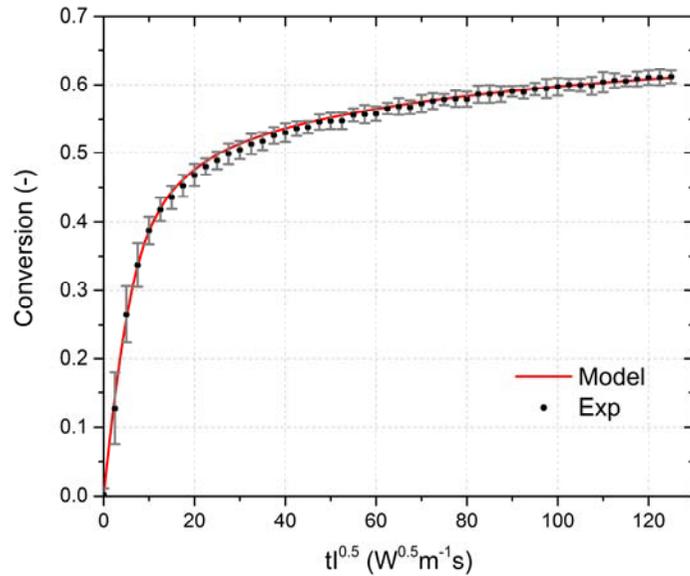
- ▲ Heat Transfer in Solids (*ht*)
 - ▲ Domains
 - ▷ Solid 1
 - ▷ Initial Values 1
 - ▷ Heat Transfer in Solids - Material
 - ▷ Heat Source - Light
 - ▷ Heat Source - Reaction
- ▲ Solid Mechanics (*solid*)
 - ▲ Domains
 - ▷ Linear Elastic Material 1
 - ▷ Initial Values 1
 - ▷ Linear Elastic Material - Material
- ▲ Photopolymerization, no diffusion (*dode*)
 - ▲ Domains
 - ▷ Distributed ODE 1
 - ▷ Initial Values 1
- ▲ Beer-Lambert Law (*cdeq*)
 - ▲ Domains
 - ▷ Convection-Diffusion Equation 1
 - ▷ Initial Values 1
- ▲ Multiphysics
 - ▷ Thermal Expansion 1 (*te1*)
 - ▷ Temperature Coupling 1 (*tc1*)
 - ▷ Thermal Expansion 2 (*te2*)

Material Characterization



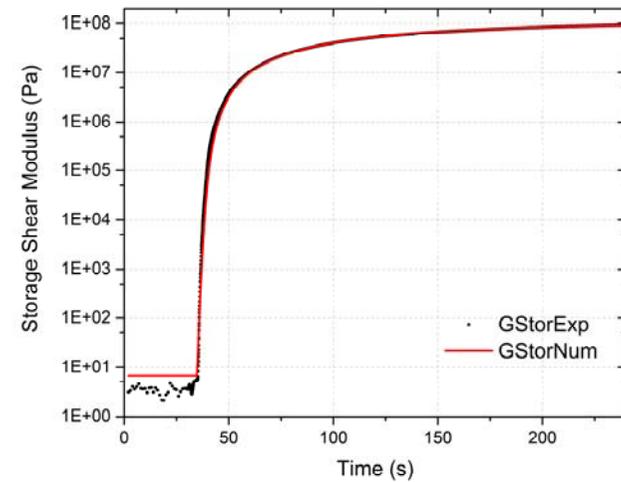
- Parameters of the kinetics model are obtained based on the experiments.

In-situ FTIR



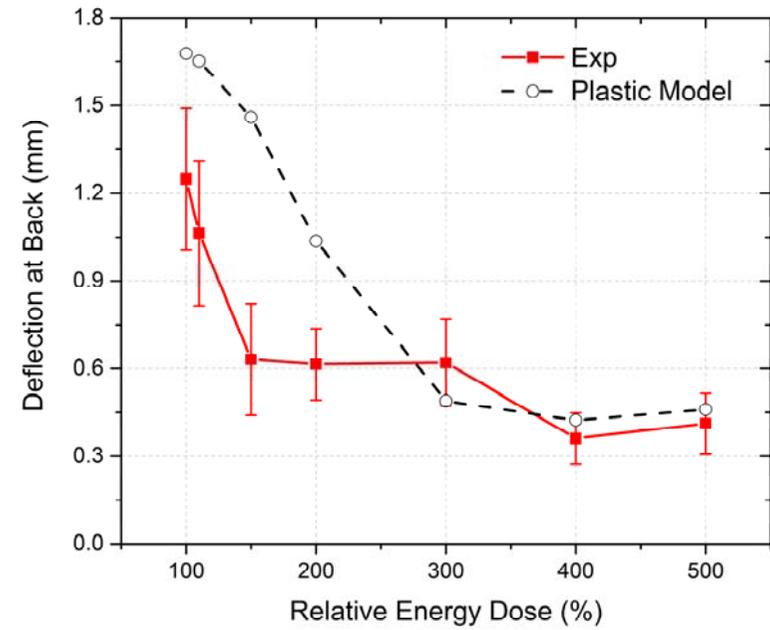
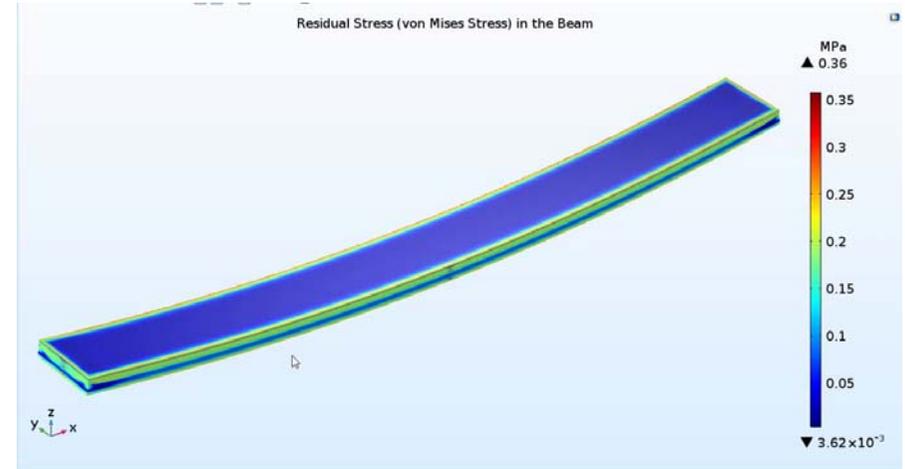
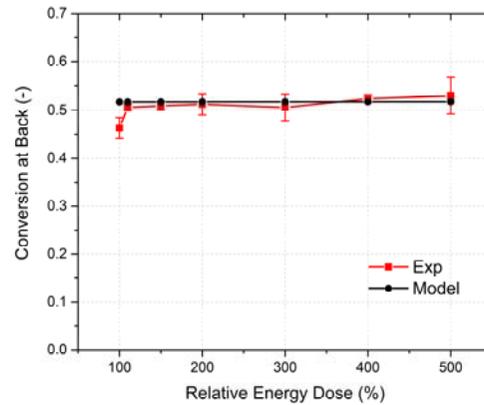
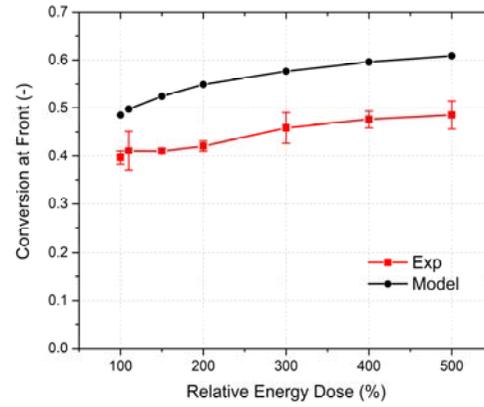
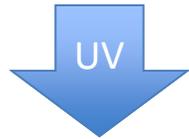
Material Contents					
Property	Variable	Value	Unit	Property group	
<input checked="" type="checkbox"/> Density	rho	rho_t	kg/m ³	Basic	
<input checked="" type="checkbox"/> Heat capacity at constant pressure	Cp	Cp_t	J/(kg·K)	Basic	
<input checked="" type="checkbox"/> Thermal conductivity	k_iso ; ki...	k_t	W/(m·K)	Basic	
<input checked="" type="checkbox"/> Coefficient of thermal expansion	alpha_is...	alpha_t	1/K	Basic	
<input checked="" type="checkbox"/> Bulk modulus	K	Km_t	N/m ²	Bulk modulus and shear modu...	
<input checked="" type="checkbox"/> Shear modulus	G	Gm_t	N/m ²	Bulk modulus and shear modu...	
Poisson's ratio	nu	nu_t	1	Basic	
Young's modulus	E	Em_t	Pa	Basic	

Rheometer



Experimental Validation

Adjust the exposure time of the last layer.



Conclusions and Outlook

- With COMSOL, a Multiphysics model was developed to investigate effects of **process conditions** and **material compositions** on **deformation** and **residual stress** of a **multi-layered DLP-printed** product.
- Required parameters can be obtained based on commercial-available experimental set-up. It gives a possibility for **standardization**.
- Validation showed a **good agreement** if a non-linear material model (plasticity) was adopted.
- We are
 - improving process conditions and new designs based on the developed model.
 - improving the accuracy and the computational cost of the model.
 - applying this model to other photo-polymers.
 - ...



Thank you for your attention!